

27. The process according to claim 23, wherein the metal etching stop layer comprises a material selected from the group consisting of Ti, Pt, Ni and combinations thereof.

28. The process according to claim 23, wherein the metal etching stop layer is applied to the substrate by PVD or CVD processes. --

REMARKS

Claims 23-28 are presently pending in the application.

The above amendments are being made to delete the claims which were elected and prosecuted in the parent application and to place the specification in better form. In particular, the cross-reference to the parent application has been inserted. New claims 26-28 have been added to further define the invention. No new matter has been added by these amendments, and entry and an early examination are respectfully requested.

Respectfully submitted,

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12/7/2000

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